



Device Material Content

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com					Package Code: BBG256		Assembly: ASEK Size (mm): 14 x 14 Lead pitch (mm): 0.8 MSL: 3 Reflow max (°C): 260	
Package: 256 caBGA Total Device Weight 327.642 Milligrams					Products: XO4D			
June 2026	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	4.73%	15.497	4.730%	15.497	Silicon chip	7440-21-3	100.00%	
Mold Compound	32.01%	104.874	24.007% 4.001% 1.921% 1.921% 0.160%	78.656 13.109 6.292 6.292 0.524	Aluminum oxide Silica (Fused) Epoxy resin Phenol resin Carbon Black	1344-28-1 60676-86-0 - - 1333-86-4	75.00% 12.50% 6.00% 6.00% 0.50%	Mold Compound: Kyocera KE-G1250AHT
D/A Epoxy	1.70%	5.570	1.463% 0.101% 0.084% 0.017% 0.032% 0.003%	4.795 0.330 0.274 0.056 0.105 0.010	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxyalkane ether 2-[[[2,2 bis[[[1-oxoallyloxy]methyl]butoxy]methyl] 2- ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 - 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% - 1.88% 0.19%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	0.57%	1.870	0.551% 0.018% 0.002%	1.805 0.058 0.007	Copper (Cu) Palladium (Pd) Gold (Au)	7440-50-8 7440-05-3 7440-57-5	96.55% 3.10% 0.35%	Au coated PCC, 0.02mm dia
Solder Balls	21.84%	71.554	21.075% 0.655% 0.109%	69.050 2.147 0.358	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate: Core	13.702%	44.895	2.839% 1.548% 1.548% 1.548% 1.118% 5.100%	9.301 5.073 5.073 5.073 3.664 16.711	Continuous Filament Fiber Glass Bismaleimide Triazine Cyanic acid (1-methylethylidene)di-4,1-phenylene ester homopolymer Other Resin Aluminum Hydroxide Copper	65997-17-3 105391-33-1 25722-66-1 - 9003-36-5 21645-51-2 7440-50-8	20.72% 11.30% 11.30% - 11.30% 8.16% 37.22%	BT Resin CCL-HL832NX-A
Solder mask	6.66%	21.820	3.650% 1.279% 1.279% 0.293% 0.033% 0.033% 0.093%	11.957 4.189 4.1895 0.9601 0.1091 0.109 0.3055	Plastic: PAK Plastic: EP Barium sulphate Talc (Magnesium silicate) Inorganic Ingredient, TS Colorant, TS Additives, TS	- - 7727-43-7 14807-96-6 - - -	54.80% 19.20% 19.20% 4.40% 0.50% 0.50% 1.40%	Solder mask PSR4000 AUS 320 Cured
Copper Foil	18.79%	61.562	17.506% 1.056% 0.228%	57.356 3.460 0.746	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	93.17% 5.62% 1.21%	
100.000%		327.642	100.000%	327.642				

Note:

Lattice regards this materials information to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Lattice subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Lattice has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Lattice products.

www.latticesemi.com

